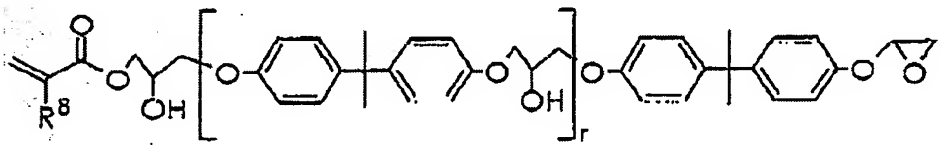
Amendments to the Claims:

This listing of claims will replace all prior versions, and listings, of claims in the application:

Listing of Claims:

1. (Previously amended) A phosphazene compound, obtained by reacting a phenoxyphosphazene compound (A-1) having a phenolic hydroxyl group and/or a cross-linked phenoxyphosphazene compound (A-2) obtained by cross-linking the phenoxyphosphazene compound (A-1) with an epoxy compound (B) having an unsaturated double bond, wherein the phosphazene compound has an unsaturated double bond and a phenolic hydroxyl group in its molecule; and

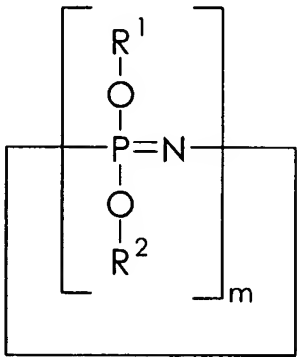
the epoxy compound (B) is at least one epoxy compound selected from the group consisting of glycidylmethacrylate, glycidylacrylate, allylglycidylether, glycidylvinylether, and a compound represented by the following formula (10)



... (10)

wherein r represents an integer ranging from 0 to 40, and R^8 represents H or a methyl group.

2. (Original) The phosphazene compound as set forth in claim 1, wherein the phenoxyphosphazene compound (A-1) is a circular phenoxyphosphazene compound (A-11) represented by formula (1)



... (1)

where m represents an integer ranging from 3 to 25, and each of R^1 and R^2 represents a phenyl group or a hydroxyphenyl group, and a single molecule has one or more hydroxyphenyl groups.

3 - 5. (Canceled)

6. (Previously presented) A photosensitive resin composition, comprising at least the phosphazene compound as set forth in claim 1 and a soluble polyimide resin (D) which is soluble in an organic solvent.

7. (Original) The photosensitive resin composition as set forth in claim 6, further comprising a photoreaction initiator (E-1).

8. (Previously presented) A photosensitive resin composition, comprising at least the phosphazene compound as set forth in claim 1 and a photoreaction initiator (E-1).

9. (Previously presented) The photosensitive resin composition as set forth in claim 6, further comprising a compound having a carbon-carbon double bond (E-4).

10. (Original) The photosensitive resin composition as set forth in claim 6, wherein 1 wt% or more of the soluble polyimide resin (D) is dissolved in at least one kind of an organic solvent selected from dioxolane, dioxane, tetrahydrofuran, N,N-dimethylformamide, N,N-dimethylacetamide, and N-methyl-2-pyrrolidone at temperature ranging from room temperature to 100°C.

11. (Previously presented) A photosensitive resin film, being formed by using the photosensitive resin composition as set forth in claim 6.

12. (Original) The photosensitive resin film as set forth in claim 11, being used as a print wiring board adhesive sheet, a photosensitive cover lay film, a print wiring insulative protection film, or a print wiring board substrate.

13 - 28. (Canceled)